Product Change Notification - KSRA-21MVRA169

Date: 14 Jul 2017

Product Category: Driver / Interface ICs

Notification subject: CCB 2784 and CCB 2784.001 Initial Notice: Qualification of MMT assembly site for selected Micrel products available in 20L and 18L PDIP packages using CRM-1064L die attach and GE800 mold compound.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT assembly site for selected Micrel products available in 20L PDIP and 18L PDIP packages using CRM-1064L die attach and G800 mold compound material.

Pre Change:
20L PDIP Package: Assembled at UNIB assembly site using CRM-1076NS die attach and GE600 molding compound material
18L PDIP Package: Assembled at ANAP assembly site using 84-1LMISR4 die attach and GE600 molding compound material

Post Change:
Both 20L PDIP and 18L PDIP Packages: Assembled at MMT assembly site using CRM-1064L die attach and G800 molding compound material

Pre and Post Change Summary:

	Pre Change		Post Change
	20L PDIP package	18L PDIP package	20L and 18L PDIP Packages
Assembly Site	UNIB Assembly Site	ANAP Assembly Site	MMT Assembly Site
Wire material	Au wire	Au wire	Au wire
Die attach material	CRM-1076NS	84-1LMISR4	CRM-1064L
Molding compound material	G600	G600	GE800
Lead frame material	C194	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying MMT assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
August 14, 2017 (1733)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	November 2016				-->	July 2017					August 2017				
Workweek	45	46	47	49		26	27	28	29	30	31	32	33	34	35
Initial PCN Issue Date		X													
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date													X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
November 11, 2016: Issued initial notification.
July 14, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on August 14, 2017

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-21MVRA169_Affected_CPN.pdf
PCN_KSRA-21MVRA169_Qual Report.pdf
PCN_KSRA-21MVRA169_Affected_CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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PCN_KSRA-21MVRA169- CCB 2784 and 2784.001 Final Notice: Qualification of MMT assembly site for selected Micrel products available in 20L 18L PDIP packages using CRM-1064L die attach GE800 mold compound material.

Affected Catalog Part Number (CPN)

PCN_KSRA-21MVRA169
CATALOG_PART_NBR
MIC2981/82YN
MIC5841YN
MIC5842YN
MIC58P42YN
MIC59P60YN

QUALIFICATION REPORT SUMMARY

PCN #: KSRA-21MVRA169

Date:

May 26, 2017

Qualification of MMT assembly site for selected Micrel products available in 20L PDIP package using CRM-1064L die attach and GE800 mold compound material. The 18L PDIP package will qualify by similarity at MMT assembly site.

Device Description:

Device	MIC59P60YN
Mask#	20850
Process	BCDM

Package Information

Package Type	PDIP-20L
Package Body Size	300 mils
Package Code	G6X
MP Codes	208507G6XA01

Subcon Location	MMT (Thailand)
Lead frame	
• Paddle size	160x200 mils
• Material	CDA194
• Surface	Ag Spot Plated
• Treatment	None
• Process	Stamped
• Lead lock	Yes
• Part Number	10102009
Wire	
• Material	Au
Die Attach Epoxy	
• Part Number	CRM-1064L
• Conductive	Yes
Mold Compound	
• Part Number	GE800
Lead finish	100% Matte Tin

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-174100818.000	TMPE217178950.210	1701C35
MMT-174100819.000	TMPE217178950.210	1701C36
MMT-174100820.000	TMPE217178950.210	1701E60

Qualification Data:

PACKAGE QUALIFICATION RESULTS						
TEST DESCRIPTION	**METHOD CONDITIONS**	**TRACE CODE**	**LOT ID.**	**96 HR Rej / Pass**	**COMMENTS**	
UHAST	JESD22-A118 Ta = +130°C/85%RH	1701C35 1701C36 1701E60	MMT-174100818.000 MMT-174100819.000 MMT-174100820.000	0/82 0/82 0/82		
TEST DESCRIPTION	**METHOD CONDITIONS**	**TRACE CODE**	**LOT ID.**	**500 CYC Rej / Pass**	**COMMENTS**	
TEMP CYCLE	JESD22-A104 Ta = -65°C / +150°C	1701C35 1701C36 1701E60	MMT-174100818.000 MMT-174100819.000 MMT-174100820.000	0/82 0/82 0/82		
TEST DESCRIPTION	**METHOD CONDITIONS**	**TRACE CODE**	**LOT ID.**	**1008 HR Rej / Pass**	**COMMENTS**	
HTSL	JESD22-A103 Ta = +150°C	1701C35 1701C36 1701E60	MMT-174100818.000 MMT-174100819.000 MMT-174100820.000	0/50 0/50 0/50		
TEST DESCRIPTION	**METHOD CONDITIONS**	**TRACE CODE**	**LOT ID.**	**Rej / Pass**	**Pass/Fail**	**COMMENTS**
Wire Bond Pull	Mil. Std 883, Method 2011	1701C35 1701C36 1701E60	MMT-174100818.000 MMT-174100819.000 MMT-174100820.000	0/35 wires 0/35 wires 0/35 wires	Pass Pass Pass	
TEST DESCRIPTION	**METHOD CONDITIONS**	**TRACE CODE**	**LOT ID.**	**Rej / Pass**	**Pass/Fail**	**COMMENTS**
Wire Bond Shear	AEC-Q100-001	1701C35 1701C36 1701E60	MMT-174100818.000 MMT-174100819.000 MMT-174100820.000	0/35 bonds 0/35 bonds 0/35 bonds	Pass Pass Pass	